COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

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<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-00459</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
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<td>GENERATED: 6/12/2015 2:32:22 PM</td>
<td>TEXAS INSTRUMENTS</td>
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